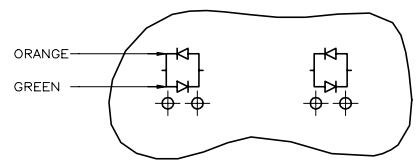
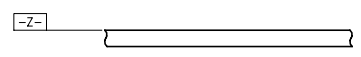
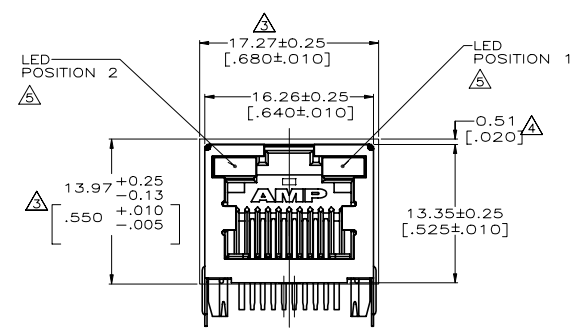
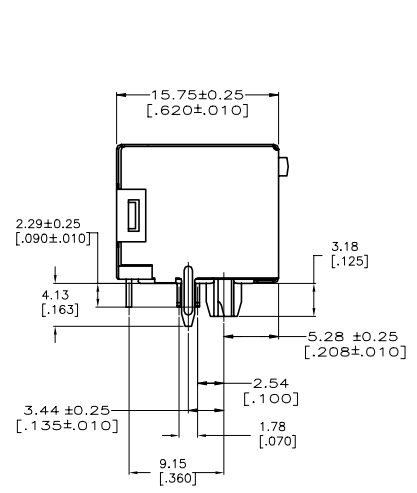
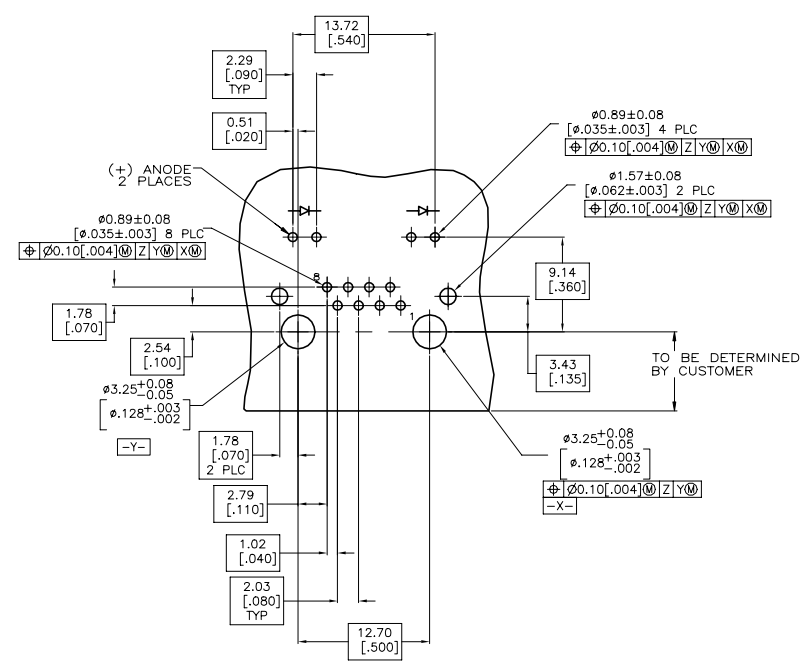


REVISIONS			
REV	DATE	DESCRIPTION	BY
F4	29AUG2020	ECO-18-014918	RR SH



LED CURRENT DIAGRAM
1116075-7 ONLY



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

- MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC,
COLOR: BLACK, UL94V-0
TERMINALS - 0.36[.014] THICK PHOS BRONZE
PLATED WITH 3.81µm[.000150] MIN THICK
BRIGHT TIN LEAD IN SOLDER AREA, 1.27µm[.000050]
MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE
TERMINAL PLATED WITH 1.27µm[.000050] MIN
THICK NICKEL.
SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY
PREPLATED WITH 1.27µm[.000050] MIN SATIN
NICKEL WITH 2.03µm[.000080] MIN TIN POST
DIPPED ON PCB GROUND TABS
LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY
LENS, 0.51 X 0.51[.020 X .020] CARBON STEEL
WIREFRAME LEADS PLATED WITH 8.89µm[.000350]
TIN/COPPER OVER 2.03µm[.000080] SILVER OVER
1.02µm[.000040] NICKEL UNDERPLATE OVER
2.03µm[.000080] COPPER UNDERPLATE
 - JACK CAVITY CONFORMS TO FCC RULES AND
REGULATIONS PART 68, SUBPART F.
- △ RECOMMENDED PANEL OPENING DIMENSIONS.
 - △ RECOMMENDED CLEARANCE BETWEEN TOP OF CONNECTOR
AND TOP PANEL OPENING.
 - △ SEE TABLE FOR COLOR OF LEDS AND NUMBER
REQUIRED.
 - 6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT
IR REFLOW SOLDERING PROCESS COMPATIBLE.
 - △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

INDICATOR COLOR	POSITION 2	POSITION 1	PART NUMBER
OBsolete	YELLOW/GREEN	YELLOW/GREEN	-1116075-8-
OBsolete	ORANGE/GREEN	ORANGE/GREEN	-1116075-7-
OBsolete	YELLOW	YELLOW	-1116075-6-
OBsolete	GREEN	GREEN	-1116075-5-
OBsolete	GREEN	YELLOW	-1116075-4-
△ OBsolete	YELLOW	-	-1116075-3-
OBsolete	-	GREEN	-1116075-2-
SUPERSEDED	YELLOW	GREEN	-1116075-1-

THIS DRAWING IS A CONTROLLED DOCUMENT.

DATE: 11-14-2014	REV: 1	BY: RR	CHK: SH
DATE: 11-14-2014	REV: 1	BY: RR	CHK: SH

TE Connectivity

INVERTED MODULAR JACK ASSEMBLY,
1X1, SHIELDED, LED

114-2154

108-1163-4

0.000000

100779

1116075

SCALE: 4:1

SHEET 1 OF 1

REV: F4